



Backside: Drain

All dimensions in mils.

Die Geometry	Dimensions			Backside Metal	Bonding Pads ²		Recommended Assembly Material		
	Length ¹	Width ¹	Thickness		Material	Size	Wire ³	Wire Size ³	Preform
VF15	37	37	11 ± 1.5	Au	Al-Cu-Si	4.3 x 5.1	Al or Au	1.3	Epoxy or Au-Si Eutectic

Notes:

1. Maximum values
2. Al-Cu-Si is used for higher operating current densities. Bond pad size represents smaller gate pad.
3. Bond wire size and material depends on AuTCB, TSB or Al USB.